

isc N-Channel MOSFET Transistor

IXFH80N65X2

• FEATURES

- With TO-247 packaging
- With low gate drive requirements
- Easy to drive
- 100% avalanche tested
- Minimum Lot-to-Lot variations for robust device performance and reliable operation

• APPLICATIONS

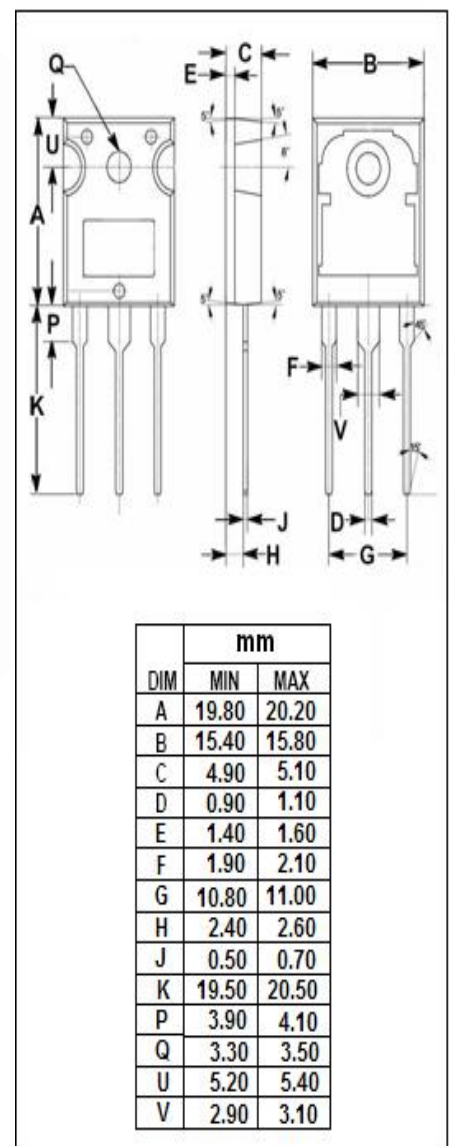
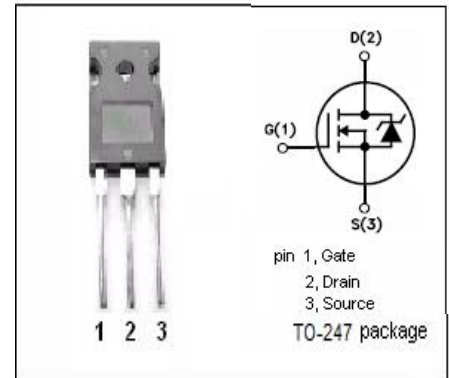
- Switching applications

• ABSOLUTE MAXIMUM RATINGS($T_a=25^{\circ}\text{C}$)

SYMBOL	PARAMETER	VALUE	UNIT
V_{DS}	Drain-Source Voltage	650	V
V_{GS}	Gate-Source Voltage	± 30	V
I_D	Drain Current-Continuous	80	A
I_{DM}	Drain Current-Single Pulsed	160	A
P_D	Total Dissipation	890	W
T_j	Operating Junction Temperature	-55~150	$^{\circ}\text{C}$
T_{stg}	Storage Temperature	-55~150	$^{\circ}\text{C}$

• THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	MAX	UNIT
$R_{th(ch-c)}$	Channel-to-case thermal resistance	0.15	$^{\circ}\text{C/W}$



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ELECTRICAL CHARACTERISTICS

 $T_c=25^{\circ}\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V; I_D=1.0mA$	650			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}; I_D=4.0mA$	3.5		5.0	V
$R_{DS(on)}$	Drain-Source On-Resistance	$V_{GS}=10V; I_D=40A$			38	$m\Omega$
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 30V; V_{DS}=0V$			± 0.1	μA
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=650V; V_{GS}=0V; @T_c=25^{\circ}\text{C}$ $V_{DS}=650V; V_{GS}=0V; T_c=150^{\circ}\text{C}$			50 3000	μA
V_{SDF}	Diode forward voltage	$I_{SD}=80A, V_{GS}=0V$			1.4	V